

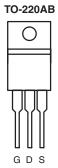
## N-Channel 100-V (D-S) 175 °C MOSFET

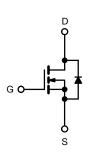
PRODUCT SUMMARY					
V <sub>DS</sub> (V)	100				
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0. 009				
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0. 020				
I <sub>D</sub> (A)	100				
Configuration	Single				

#### **FEATURES**

- TrenchFET® Power MOSFET
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T <sub>A</sub> = 25 °C, unless otherwise noted							
Parameter		Symbol	Limit	Unit			
Drain-Source Voltage		V <sub>DS</sub>	100	V			
Gate-Source Voltage		V <sub>GS</sub>	± 20	V			
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C	I <sub>D</sub>	100	A			
	T <sub>C</sub> = 125 °C	טי	75 <sup>a</sup>				
Pulsed Drain Current	I <sub>DM</sub>	300	A				
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	75				
Single Pulse Avalanche Energy <sup>b</sup>	L = 0.1 IIII1	E <sub>AS</sub>	280	mJ			
Marrian Danier Dissipation	$T_C = 25$ °C (TO-220AB and TO-263)	$P_{D}$	250 <sup>c</sup>	w			
Maximum Power Dissipation <sup>b</sup>	T <sub>A</sub> = 25 °C (TO-263) <sup>d</sup>		3.75	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \			
Operating Junction and Storage Temperat	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C				

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient	PCB Mount (TO-263) <sup>d</sup>	R <sub>thJA</sub>	40	°C/W		
Junction-to-Ambient	Free Air (TO-220AB)	' 'thJA	62.5			
Junction-to-Case		R <sub>thJC</sub>	0.6			

#### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



Parameter	Symbol	Symbol Test Conditions			Max.	Unit	
Static							
Drain-Source Breakdown Voltage	ource Breakdown Voltage $V_{DS}$ $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		100			v	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2		4	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V	1		1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μΑ	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A		0.009			
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 20 A		0.020		_	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C		0.023		Ω	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C		0.030			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A	25			S	
Dynamic <sup>b</sup>				L			
Input Capacitance	C <sub>iss</sub>			4700		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		665			
Reverse Transfer Capacitance	C <sub>rss</sub>	1		265			
Total Gate Charge <sup>c</sup>	$Q_g$			105	160		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 85 \text{ A}$		17		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>	1		23			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			12	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, R_{L} = 0.6 \Omega$		90	135		
Turn-Off DelayTime <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 85 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		55	85	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>	1		130	195		
Source-Drain Diode Ratings and Char	acteristics T <sub>C</sub>	= 25 °C <sup>b</sup>					
Continuous Current	Is				85		
Pulsed Current	I <sub>SM</sub>				240	Α	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 85 A, V <sub>GS</sub> = 0 V		1.0	1.5	٧	
Reverse Recovery Time	t <sub>rr</sub>			85	140	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 50 A, dI/dt = 100 A/μs		4.5	7	Α	
Reverse Recovery Charge	Q <sub>rr</sub>	7		0.17	0.35	μC	

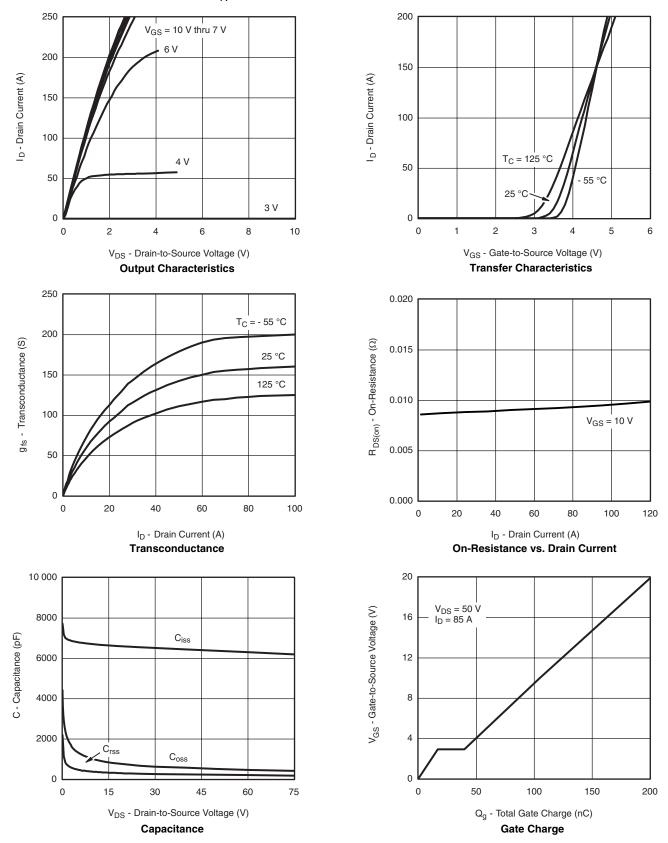
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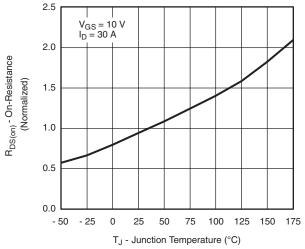
**TYPICAL CHARACTERISTICS**  $T_A = 25$  °C, unless otherwise noted



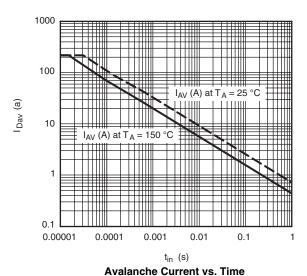
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### **TYPICAL CHARACTERISTICS** $T_A = 25 \, ^{\circ}C$ , unless otherwise noted

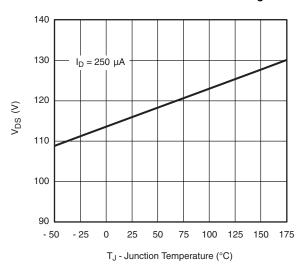


On-Resistance vs. Junction Temperature



T<sub>J</sub> = 150 °C T<sub>J</sub> = 25 °C T<sub>J</sub> = 25 °C T<sub>J</sub> = 25 °C V<sub>SD</sub> - Source-to-Drain Voltage (V)

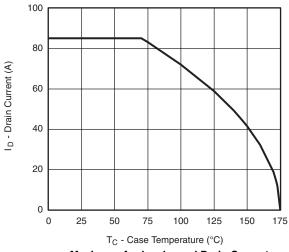
Source-Drain Diode Forward Voltage

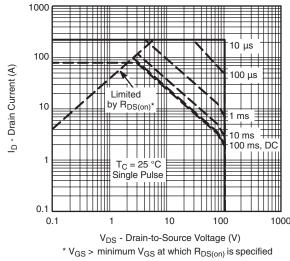


T<sub>J</sub> - Drain-Source Breakdown vs. Junction-Temperature



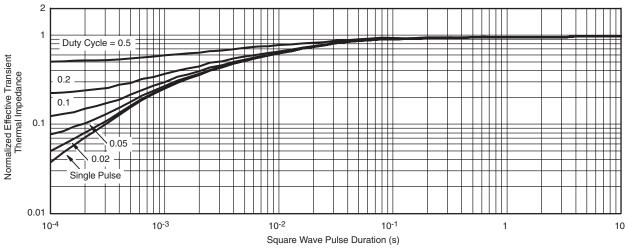
### THERMAL RATINGS





**Maximum Avalanche and Drain Current** vs. Case Temperature

**Safe Operating Area** 



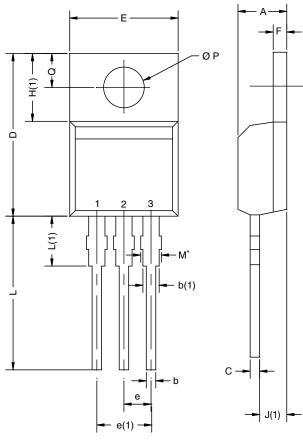
Normalized Thermal Transient Impedance, Junction-to-Case

服务热线:400-655-8788

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# **TO-220AB**



<b>-</b>	e(1)	-		
		$\overline{)}$		
			_	D2

	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
D2	12.19	12.70	0.480	0.500	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471					

### Note

 $<sup>^{\</sup>star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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